

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
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Application Number:	14140546																
CORRESPONDENCE DATA																	
Fax Number:	(703)997-4517																
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Email:	Patent.admin.uspto.cr@naipo.com																
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>																	
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ATTORNEY DOCKET NUMBER:	NAUP1414USA1																
NAME OF SUBMITTER:	KATE YEH																

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Signature:	/KATE YEH/
Date:	01/23/2014
Total Attachments: 3 source=1860481#page1.tif source=1860481#page2.tif source=1860481#page3.tif	

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Ssu-I Fu Nationality: TW

Name: Wen-Tai Chiang Nationality: TW

Name: Ying-Tsung Chen Nationality: TW

Name: Shih-Hung Tsai Nationality: TW

Name: Chien-Ting Lin Nationality: TW

Name: Chi-Mao Hsu Nationality: TW

Name: Chin-Fu Lin Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"MANUFACTURING METHOD FOR SEMICONDUCTOR DEVICE HAVING METAL GATE"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____
- (e) _____ International application no. _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this DEC 13 2011 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Ssu-I Fu

Ssu-I Fu

Wen-Tai Chiang

Wen-Tai Chiang

Ying-Tsung Chen

Ying-Tsung Chen

Shih-Hung Tsai

Shih-Hung Tsai

Chien-Ting Lin

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